



Material Content Data Sheet



Sales Product Name		IPD30N12S3L-31		Issued		4. March 2019		
MA#		MA003185328						
Package		PG-TO252-3-11		Weight*		370.91 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.345	0.63	0.63	6322	6322
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		174	
	non noble metal	iron	7439-89-6	0.215	0.06		580	
	non noble metal	copper	7440-50-8	215.017	57.97	58.05	579702	580456
	non noble metal	aluminium	7429-90-5	2.494	0.67	0.67	6724	6724
wire	non noble metal	aluminium	7429-90-5	2.494	0.67	0.67	6724	6724
encapsulation	organic material	carbon black	1333-86-4	1.251	0.34		3372	
	plastics	epoxy resin	-	21.885	5.90		59003	
	inorganic material	silicondioxide	60676-86-0	101.920	27.48	33.72	274785	337160
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10083	10083
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	245	246
solder	non noble metal	tin	7440-31-5	0.054	0.01		145	
	noble metal	silver	7440-22-4	0.067	0.02		181	
	non noble metal	lead	7439-92-1	2.563	0.69	0.72	6911	7237
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		16	
	non noble metal	iron	7439-89-6	0.019	0.01		52	
	non noble metal	copper	7440-50-8	19.177	5.17	5.18	51704	51772
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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